ABSTRACT

CMP METHOD AND APPARATUS FOR SIMULTANEOUSLY POLISHING PRODUCT AND CONDITIONING THE POLISHING PAD

An improved and new substrate carrier head for use in a CMP apparatus is described. The new substrate carrier head facilitates polishing pad conditioning simultaneously with polishing product through the use of an abrasive surface built into the carrier head. The abrasive surface is incorporated into the substrate retaining ring or into a separate conditioning ring. Polishing pad life is prolonged and CMP apparatus throughput is increased thereby reducing cost of polished product.

(FIGURE 1A IS SUGGESTED FOR PUBLICATION)